



ABSOLUTE MAXIMUM RATINGS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)					
PARAMETER	TEST CONDITION	PART	SYMBOL	VALUE	UNIT
INPUT					
Reverse voltage			V_R	6	V
Forward current			I_F	60	mA
Surge current			I_{FSM}	2.5	A
Power dissipation			P_{diss}	100	mW
Derate from 25 °C				1.33	mW/°C
OUTPUT					
Peak off-state voltage		VO4154D/M	V_{DRM}	400	V
		VO4156D/H/M	V_{DRM}	600	V
RMS on-state current			I_{TM}	300	mA
Total power dissipation			P_{diss}	500	mW
Derate from 25 °C				6.6	mW/°C
COUPLER					
Storage temperature range			T_{stg}	-55 to +150	°C
Ambient temperature range			T_{amb}	-55 to +100	°C
Soldering temperature	Max. ≤ 10 s dip soldering ≥ 0.5 mm from case bottom		T_{sld}	260	°C

Note

- Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute maximum ratings for extended periods of the time can adversely affect reliability

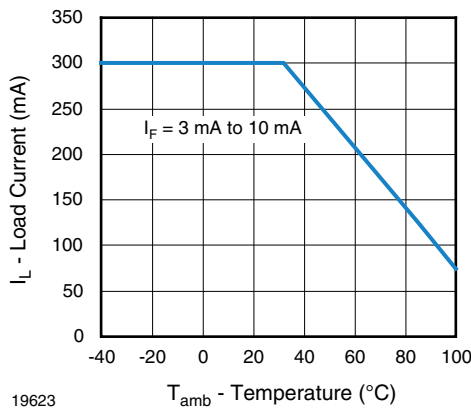


Fig. 1 - Recommended Operating Condition

THERMAL CHARACTERISTICS			
PARAMETER	SYMBOL	VALUE	UNIT
LED power dissipation	P_{diss}	100	mW
Output power dissipation	P_{diss}	500	mW
Maximum LED junction temperature	$T_{jmax.}$	125	°C
Maximum output die junction temperature	$T_{jmax.}$	125	°C
Thermal resistance, junction emitter to board	θ_{JEB}	150	°C/W
Thermal resistance, junction emitter to case	θ_{JEC}	139	°C/W
Thermal resistance, junction detector to board	θ_{JDB}	78	°C/W
Thermal resistance, junction detector to case	θ_{JDC}	103	°C/W
Thermal resistance, junction emitter to junction detector	θ_{JED}	496	°C/W
Thermal resistance, case to ambient	θ_{CA}	3563	°C/W

Note

- The thermal characteristics table above were measured at 25 °C and the thermal model is represented in the thermal network below. Each resistance value given in this model can be used to calculate the temperatures at each node for a given operating condition. The thermal resistance from board to ambient will be dependent on the type of PCB, layout and thickness of copper traces. For a detailed explanation of the thermal model, please reference Vishay's Thermal Characteristics of Optocouplers application note

ELECTRICAL CHARACTERISTICS ($T_{amb} = 25\text{ °C}$, unless otherwise specified)							
PARAMETER	TEST CONDITION	PART	SYMBOL	MIN.	TYP.	MAX.	UNIT
INPUT							
Forward voltage	$I_F = 10\text{ mA}$		V_F	-	1.2	1.4	V
Reverse current	$V_R = 6\text{ V}$		I_R	-	0.1	10	μA
Input capacitance	$V_F = 0\text{ V}$, $f = 1\text{ MHz}$		C_I	-	25	-	pF
OUTPUT							
Repetitive peak off-state voltage	$I_{DRM} = 100\text{ }\mu\text{A}$	VO4154D/M	V_{DRM}	400	-	-	V
		VO4156D/H/M	V_{DRM}	600	-	-	V
Off-state current	$V_D = V_{DRM}$, $I_F = 0\text{ A}$		I_{DRM}	-	-	100	μA
On-state voltage	$I_T = 300\text{ mA}$		V_{TM}	-	-	3	V
On-state current	$PF = 1$, $V_{T(RMS)} = 1.7\text{ V}$		I_{TM}	-	-	300	mA
Off-state current in inhibit state	$I_F = 2\text{ mA}$, V_{DRM}		I_{DINH}	-	-	200	μA
Holding current			I_H	-	-	500	μA
Zero cross inhibit voltage	$I_F = \text{rated } I_{FT}$		V_{IH}	-	-	20	V
Critical rate of rise of off-state voltage	$V_D = 0.67 V_{DRM}$, $T_J = 25\text{ °C}$		dV/dt_{cr}	5000	-	-	V/ μs
Critical rate of rise of on-state			dV/dt_{cr}	8	-	-	A/ μs
COUPLER							
LED trigger current, current required to latch output	$V_D = 3\text{ V}$	VO4154D	I_{FT}	-	-	1.6	mA
		VO4154M	I_{FT}	-	-	3	mA
		VO4156D	I_{FT}	-	-	1.6	mA
		VO4156H	I_{FT}	-	-	2	mA
		VO4156M	I_{FT}	-	-	3	mA
Common mode coupling capacitance			C_{CM}	-	0.01	-	pF
Capacitance (input to output)	$f = 1\text{ MHz}$, $V_{IO} = 0\text{ V}$		C_{IO}	-	0.8	-	pF

Note

- Minimum and maximum values were tested requirements. Typical values are characteristics of the device and are the result of engineering evaluations. Typical values are for information only and are not part of the testing requirements

SAFETY AND INSULATION RATINGS				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Climatic classification	According to IEC 68 part 1		55/100/21	
Pollution degree	According to DIN VDE 0109		2	
Comparative tracking index	Insulation group IIIa	CTI	175	
Maximum rated withstanding isolation voltage	According to UL1577, t = 1 min	V_{ISO}	4420	V_{RMS}
Maximum transient isolation voltage	According to DIN EN 60747-5-5	V_{IOTM}	8000	V_{peak}
Maximum repetitive peak isolation voltage	According to DIN EN 60747-5-5	V_{IORM}	890	V_{peak}
Isolation resistance	$T_{amb} = 25\text{ }^{\circ}\text{C}$, $V_{IO} = 500\text{ V}$	R_{IO}	$\geq 10^{12}$	Ω
	$T_{amb} = 100\text{ }^{\circ}\text{C}$, $V_{IO} = 500\text{ V}$	R_{IO}	$\geq 10^{11}$	Ω
Output safety power		P_{SO}	500	mW
Input safety current		I_{SI}	250	mA
Input safety temperature		T_S	175	$^{\circ}\text{C}$
Creepage distance	DIP-6		≥ 7	mm
Clearance distance			≥ 7	mm
Creepage distance	DIP-6, 400 mil, option 6		≥ 8	mm
Clearance distance			≥ 8	mm
Creepage distance	SMD-6, option 7		≥ 7	mm
Clearance distance			≥ 7	mm
Insulation thickness		DTI	≥ 0.4	mm

Note

- As per IEC 60747-5-5, § 7.4.3.8.2, this optocoupler is suitable for “safe electrical insulation” only within the safety ratings. Compliance with the safety ratings shall be ensured by means of protective circuits

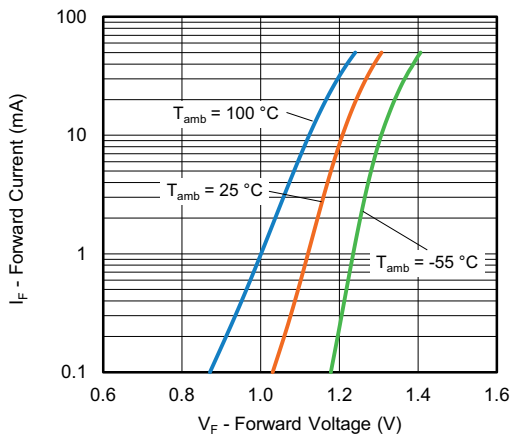
TYPICAL CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)


Fig. 2 - Diode Forward Voltage vs. Forward Current

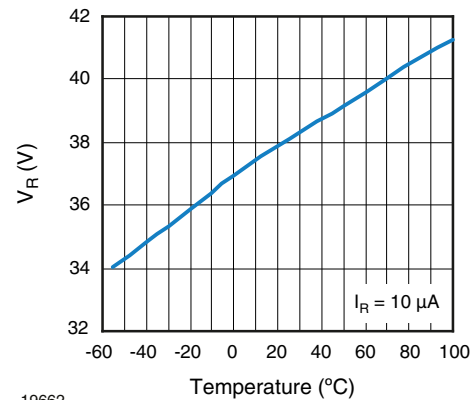


Fig. 3 - Diode Reverse Voltage vs. Temperature

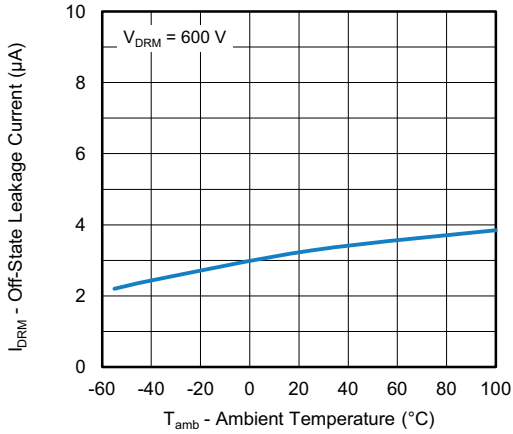


Fig. 4 - Leakage Current vs. Ambient Temperature

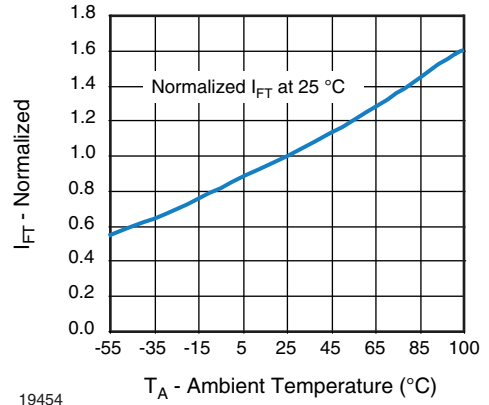


Fig. 7 - Normalized Trigger Input Current vs. Temperature

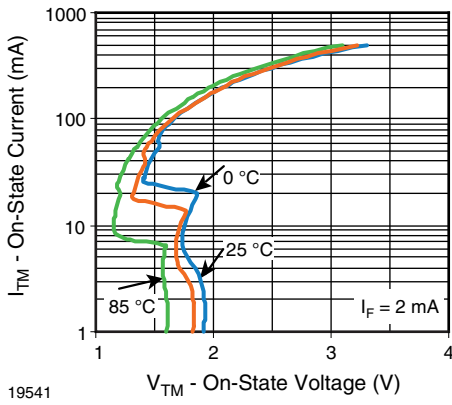


Fig. 5 - On-State Current vs. On-State Voltage

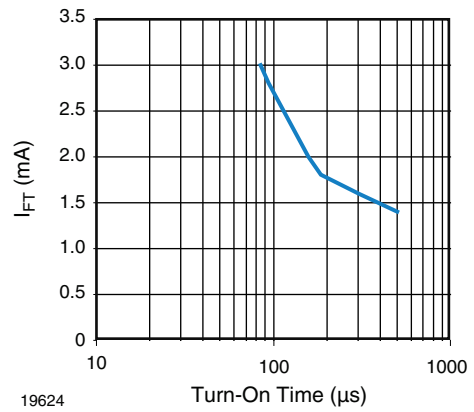


Fig. 8 - I_{FT} (mA) vs. Turn-On Time (μ s)

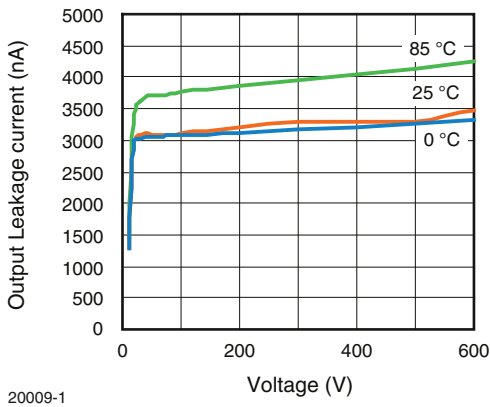


Fig. 6 - Output Off Current (Leakage) vs. Voltage

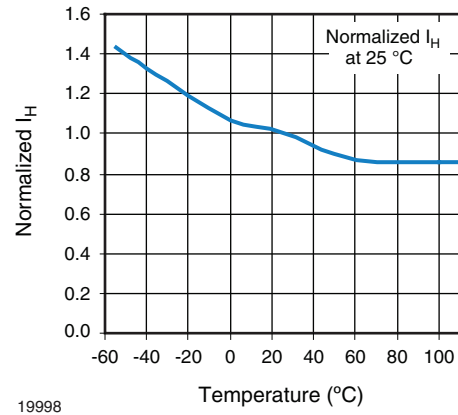


Fig. 9 - Normalized Holding Current vs. Temperature

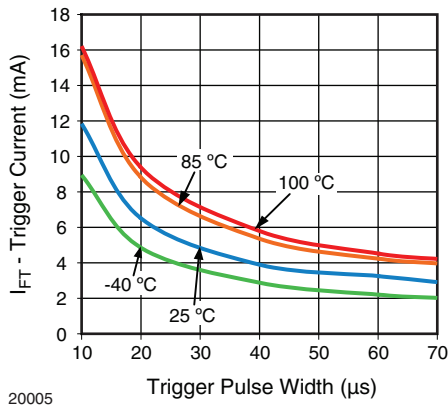
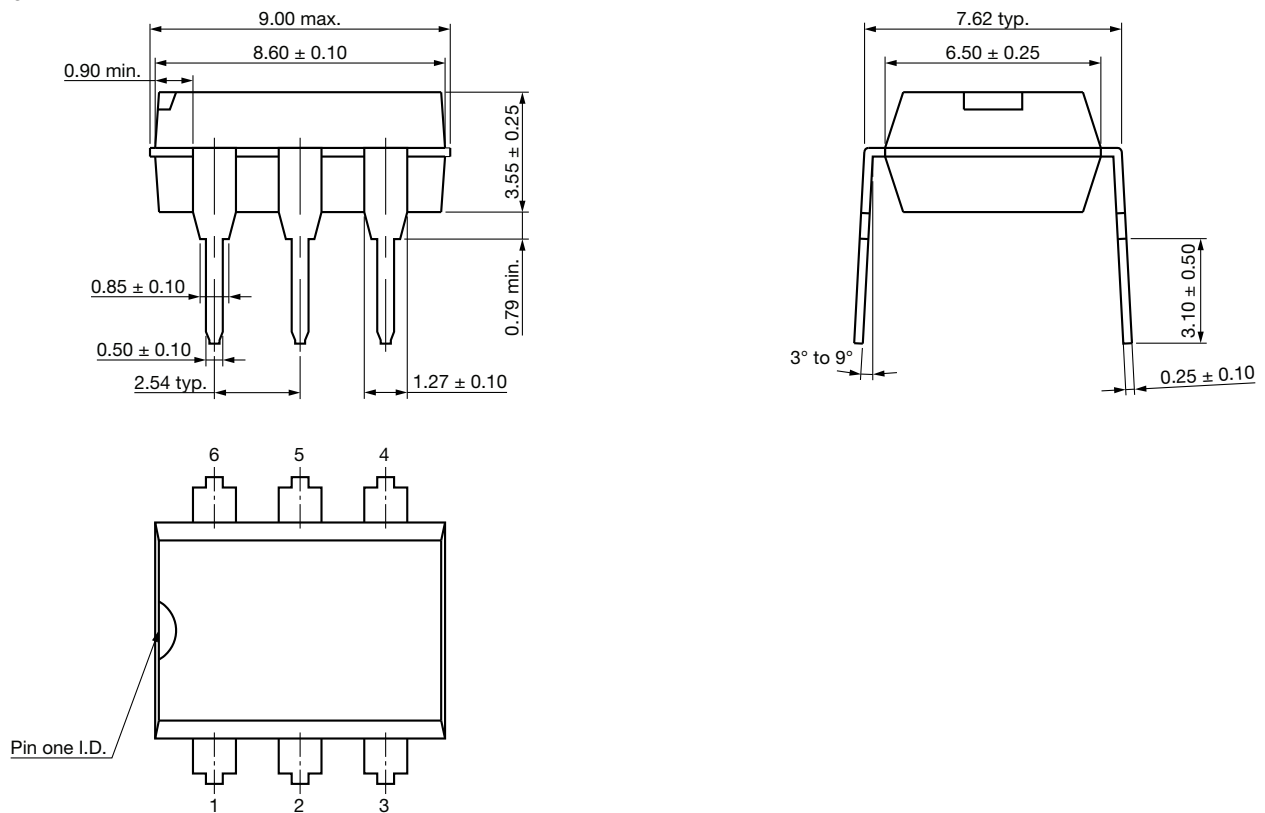


Fig. 10 - I_{FT} vs. LED Pulse Width

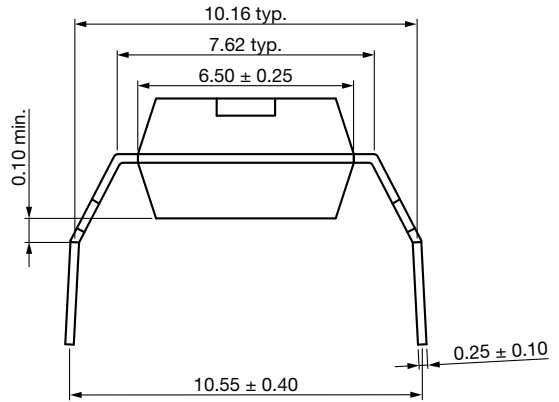
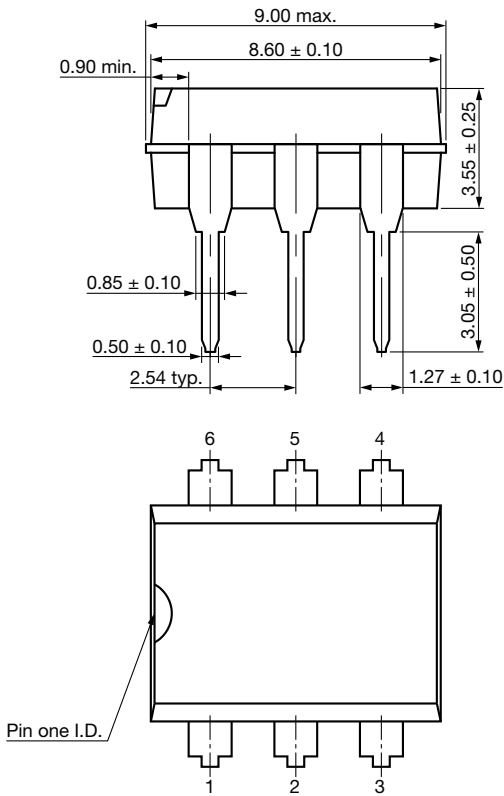
PACKAGE DIMENSIONS

DIP-6

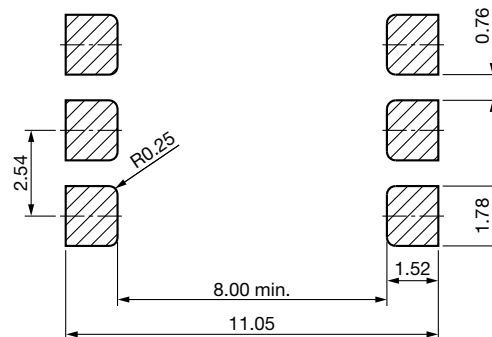
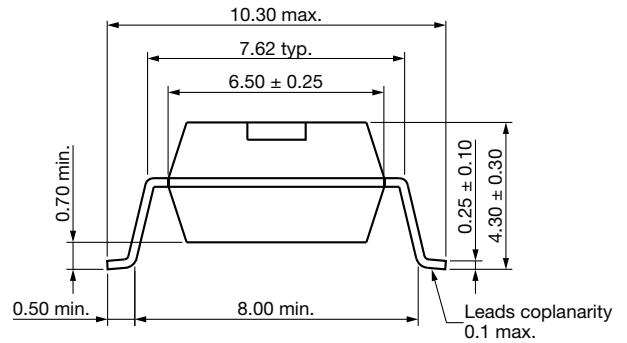
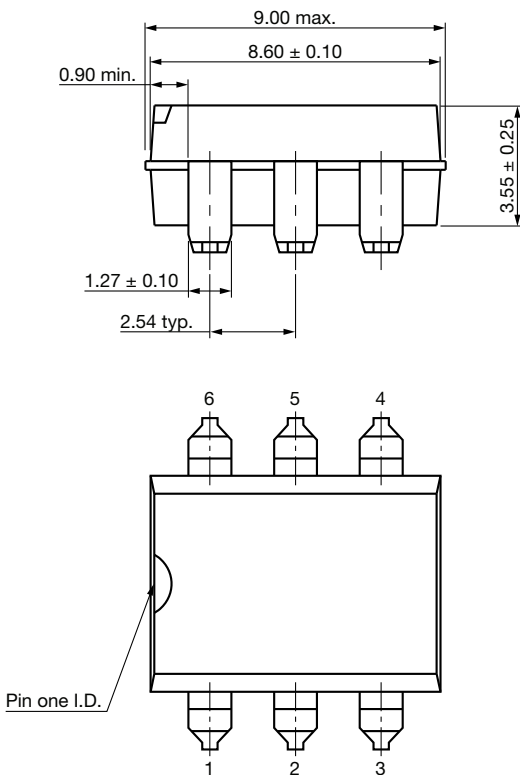




DIP-6, Option 6



SMD-6, Option 7



PACKAGE MARKING

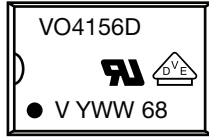


Fig. 11 - Example of VO4156D-X017T

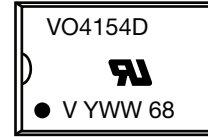


Fig. 12 - Example of VO4154D-X006

Notes

- “YWW” is the date code marking (Y = year code, WW = week code)
- The VDE logo is only marked on option 1 parts
- Tape and reel suffix (T) is not part of the package marking

PACKING INFORMATION (in millimeters)

Tube

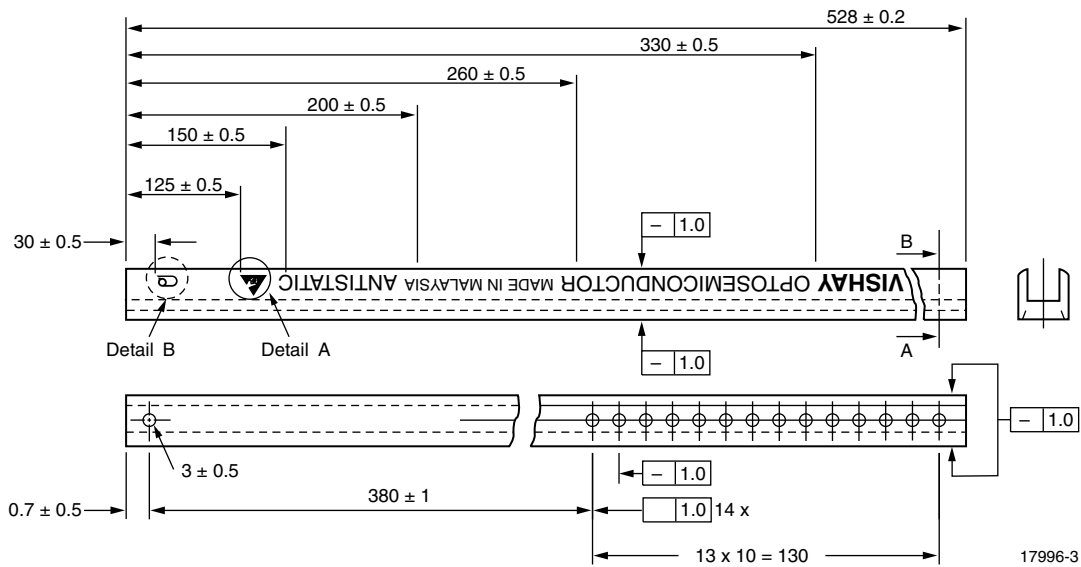


Fig. 13 - Shipping Tube Specifications for DIP-6 Packages

DEVICES PER TUBS			
TYPE	UNITS/TUBE	TUBES/BOX	UNITS/BOX
DIP-6	50	40	2000
DIP-6, option 6	50	40	2000

DIP-6

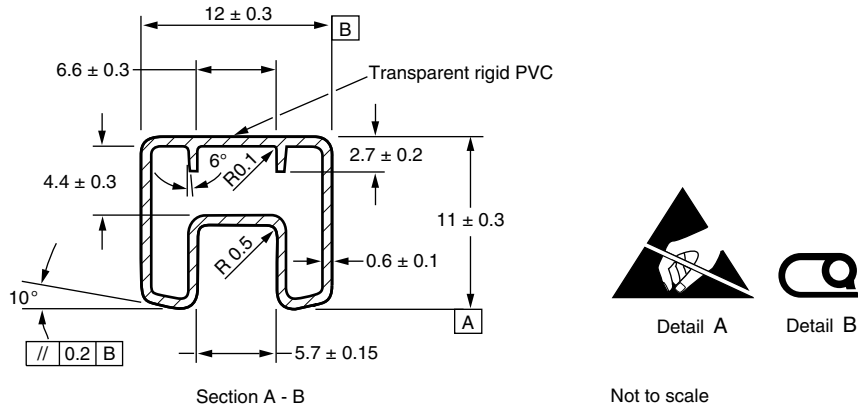


Fig. 14 - Tube Shipping Medium

DIP-6, Option 6

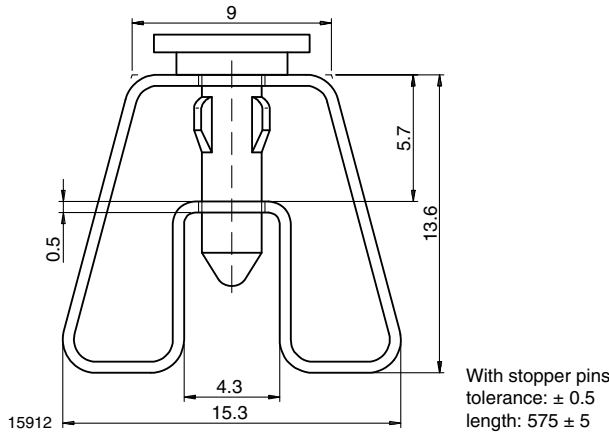


Fig. 15 - Tube Shipping Medium

Tape and Reel

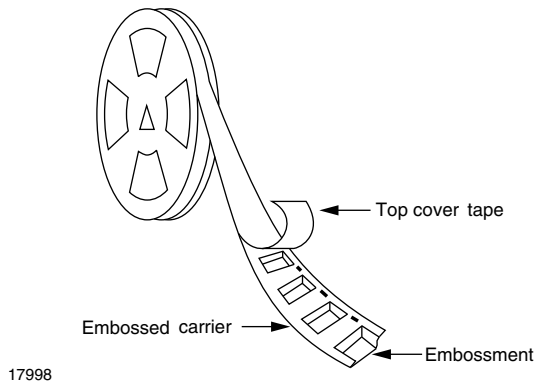


Fig. 16 - Tape and Reel Shipping Medium

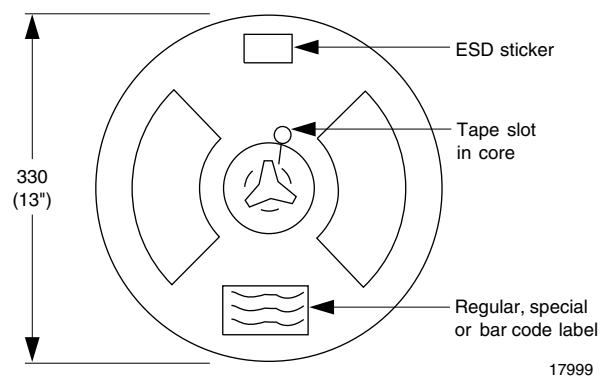


Fig. 17 - Tape and Reel Shipping Medium

SMD-6, Option 7

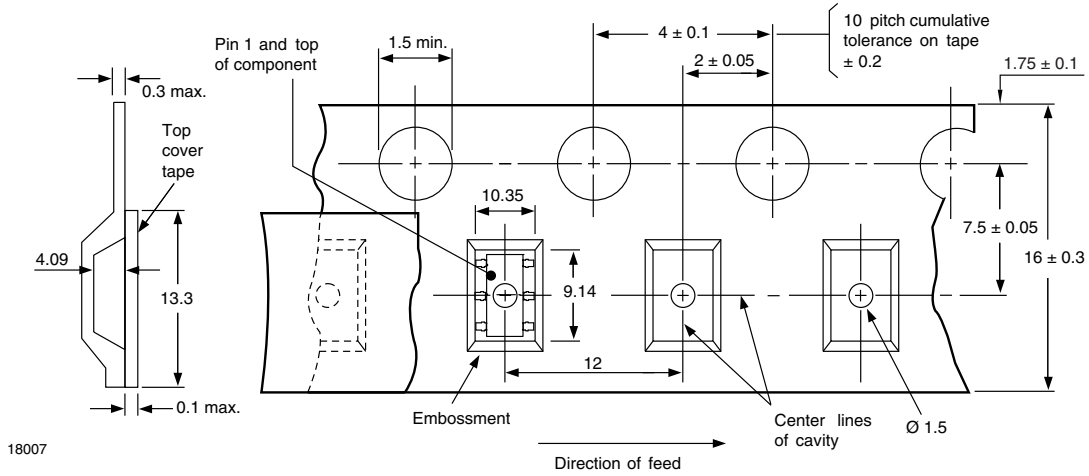


Fig. 18 - Tape and Reel Packing (1000 pieces on reel)

SOLDER PROFILES

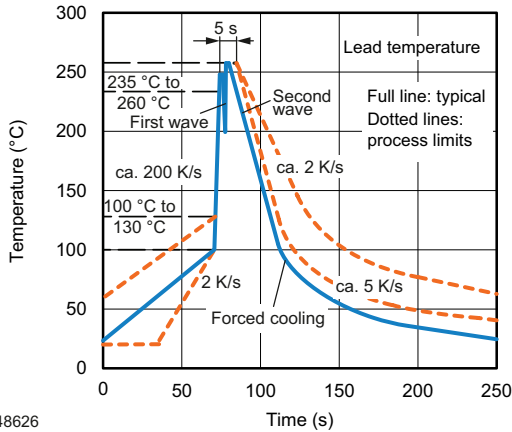


Fig. 19 - Wave Soldering Double Wave Profile According to J-STD-020 for DIP Devices

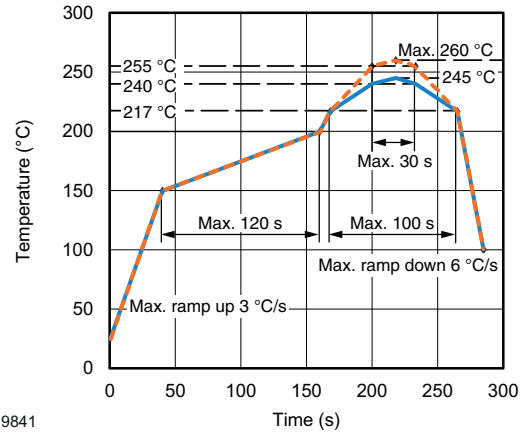


Fig. 20 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020 for SMD Devices

HANDLING AND STORAGE CONDITIONS

ESD level: HBM class 2

Floor life: unlimited

Conditions: $T_{amb} < 30\text{ °C}$, RH < 85 %

Moisture sensitivity level 1, according to J-STD-020



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